



ECP5 VIP Processor Board

Evaluation Board User Guide

FPGA-EB-02001-1.6

April 2021

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Contents

Acronyms in This Document	5
1. Introduction.....	6
1.1. Further Information	6
2. Headers and Test Connections.....	9
3. Programming Circuit.....	10
4. ECP5 Interface Support	11
4.1. Clock Interface	11
4.2. DDR3 Interface	11
4.3. Nanovesta Interface.....	11
4.4. Upstream and Downstream interface.....	12
4.5. ispClock5406D Interface	12
4.6. Debugging Interface.....	13
5. Power Supply.....	14
6. ECP5 I/O Ball Mapping to Connectors	15
7. Status Indicators	19
8. Ordering Information	20
Appendix A. ECP5 VIP Processor Board Schematics	21
Appendix B. ECP5 VIP Processor Board Bill of Materials	29
Appendix C. ECP5 VIP Processor Board Revision B.....	38
References.....	41
Technical Support Assistance	42
Revision History.....	43

Figures

Figure 1.1. Top View of ECP5 VIP Processor Board and its Key Components	7
Figure 1.2. Bottom View of ECP5 VIP Processor Board	8
Figure 3.1. Programming Block using USB Interface	10
Figure 4.1. DDR3 Interface	11
Figure 4.2. Nanovesta Connector Interface	12
Figure 4.3. Upstream and Downstream Connector	12
Figure 4.4. ispClock5406D Interface	12
Figure 5.1. Power Supply Block	14
Figure A.1. Block Diagram	21
Figure A.2. FTDI and Programming Interface	22
Figure A.3. Power Regulator Interface	23
Figure A.4. MIPI and GPIO Connector Interface	24
Figure A.5. DDR3 Interface	25
Figure A.6. SerDes Interface	26
Figure A.7. ECP5 Decoupling	27
Figure A.8. HISPI/CSI2 Connector	28
Figure C.1. DDR3 Interface Revision B	39
Figure C.2. MIPI and GPIO Connector Interface Revision B	40

Tables

Table 2.1. Headers and Test Connections	9
Table 3.1. SPI Flash Memory	10
Table 4.1. Header (J14)	13
Table 4.2. Switch (SW3)	13
Table 4.3. JTAG Connector (J1)	13
Table 5.1. Device Power Rail Summary	14
Table 6.1. Upstream Connector Mapping	15
Table 6.2. Downstream Connector Pin Mapping	16
Table 6.3. Nanovesta Connector Pin Mapping	18
Table 7.1. Status LED I/O Map	19
Table 8.1. Reference Part Number	20

Acronyms in This Document

A list of acronyms used in this document.

Acronym	Definition
CMOS	Complementary Metal-Oxide Semiconductor
CSI-2	Camera Serial Interface
DDR	Double Data Rate
DSI	Display Serial Interface
FTDI	Future Technology Devices International
GPIO	General Purpose Input/Output
I ² C	Inter-Integrated Circuit
LVDS	Low-Voltage Differential Signaling
SPI	Serial Peripheral Interface
VIP	Video Interface Platform
VTT	Tracking Termination Voltage

1. Introduction

This document describes the Lattice Semiconductor ECP5 VIP Processor Board which is a key component of Lattice's Video Interface Platform (VIP) board interconnect. Lattice VIP boards can be interconnected to create solutions for MIPI® CSI-2/DSI, SerDes, LVDS and more.

The content of this user guide includes descriptions of onboard jumper settings, programming circuit, a complete set of schematics, and bill of materials for ECP5 VIP processor board.

Key features of the ECP5 VIP processor board include:

- ECP5/5G
 - SerDes interface
 - Dual DDR3 interface
 - LVDS/MIPI Transmitter/Receiver interface
 - SPI flash configuration
 - General Purpose Input/Output
- Programming Circuit
 - Mini-B USB connector to FTDI
 - FTDI to ECP5 using JTAG
 - FTDI to ispClock using JTAG
- ispClock
 - SerDes reference clock generation interface

[Figure 1.1](#) on the next page shows the top view of the ECP5 VIP processor board and its key components. [Figure 1.2](#) shows the bottom view of the board. This document primarily describes Revision C of the ECP5 VIP Processor Board. Refer to [Appendix C](#) for a description of significant differences between Revision B and Revision C of the board.

1.1. Further Information

- For more information on boards and kits available for the VIP system, visit www.latticesemi.com/boards
- The board's key component is the ECP5™ FPGA. For details about ECP5, refer to [ECP5 and ECP5-5G Family Data Sheet \(FPGA-DS-02012\)](#).
- For the latest information about this board, demo files, further documentation and more, visit www.latticesemi.com/Products/FPGAandCPLD/ECP5.aspx
- Refer to [Appendix A](#) and [Appendix B](#) for the schematics and BOM of the ECP5 VIP processor board.

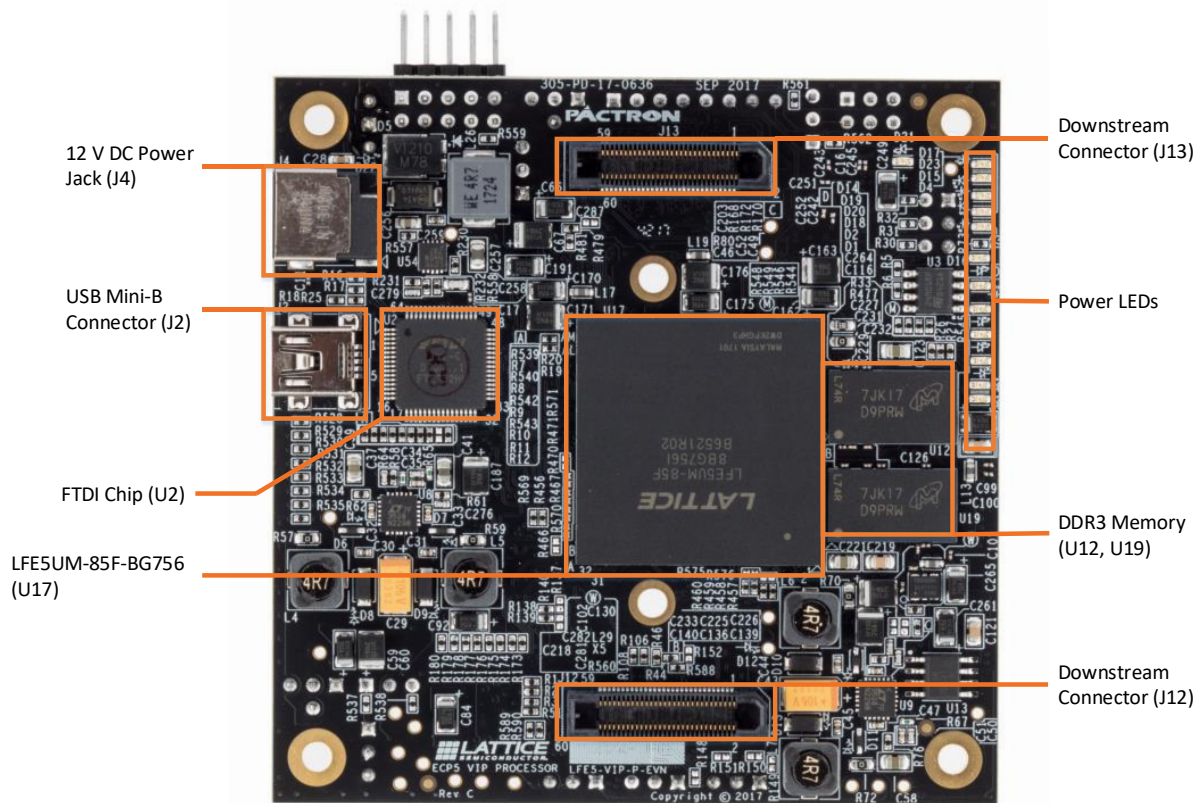


Figure 1.1. Top View of ECP5 VIP Processor Board and its Key Components

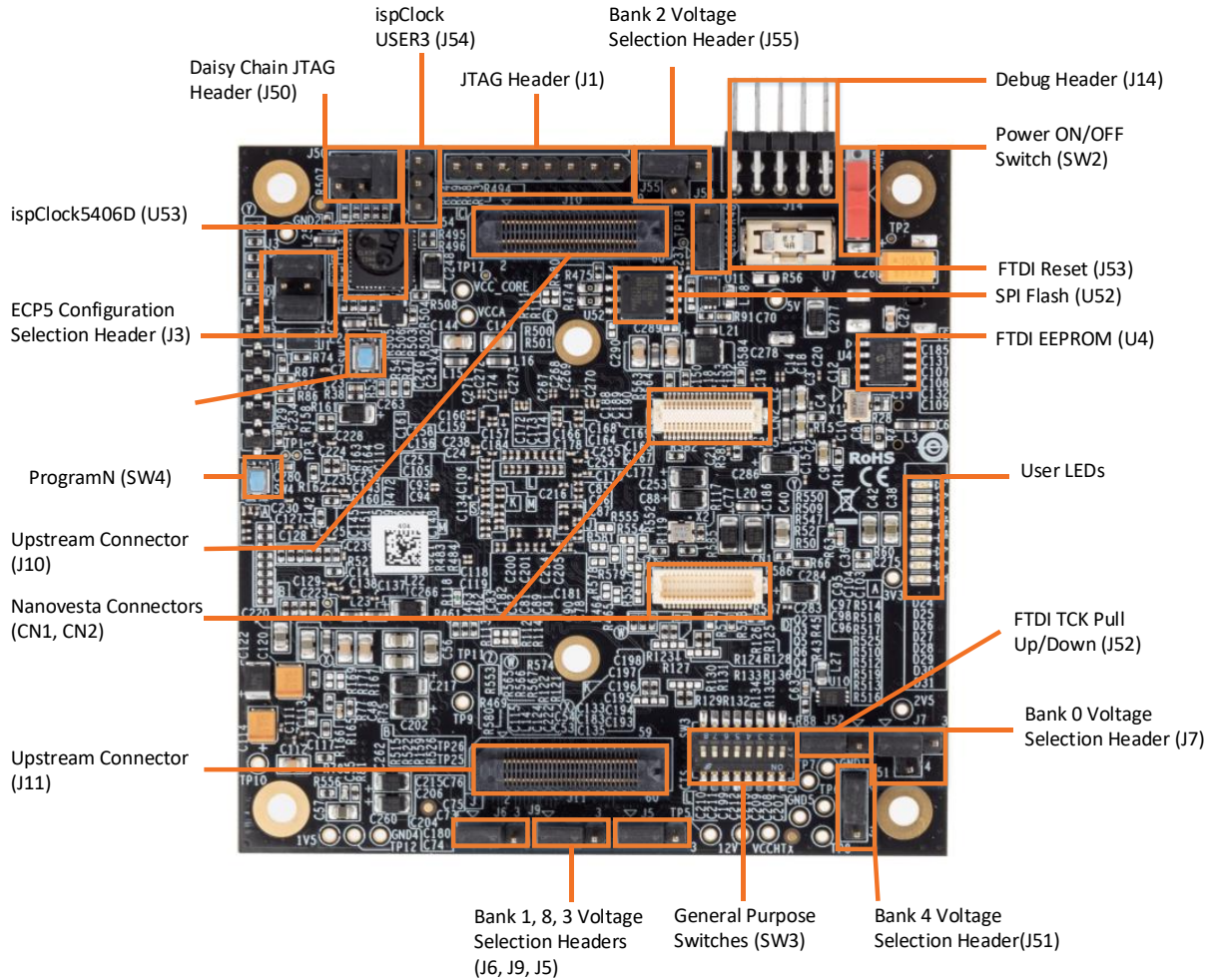


Figure 1.2. Bottom View of ECP5 VIP Processor Board

2. Headers and Test Connections

The headers and test connections on the board provide access to ECP5 VIP processor board circuits. [Table 2.1](#) lists the headers and test connectors.

Table 2.1. Headers and Test Connections

Part	Description	Setting
CN1/CN2	Nanovesta serial interface connector	—
J1	External JTAG interface	—
J2	Mini-B USB connector for programming	—
J3	ECP5 Configuration mode selection header	Refer to Schematic note in Appendix A
J4	12 V DC power jack	—
J5	ECP5 Bank 8 voltage selection	1–2 (3V3), 2–3 (2V5)
J6	ECP5 Bank 1 voltage selection	1–2 (3V3), 2–3 (2V5)
J7	ECP5 Bank 0 voltage selection	1–2 (3V3), 2–3 (2V5), 2–4 (CN1/CN2_VCC)
J9	ECP5 Bank 3 voltage selection	1–2 (3V3), 2–3 (2V5)
J10/J11	General purpose upstream connector	—
J12/J13	General purpose downstream connector	—
J14	Debug Header	—
J50	JTAG Daisy Chain connector	Refer to Schematic note in Appendix A
J51	ECP5 Banks 4 voltage selection	1–2 (3V3), 2–3 (2V5)
J52	JTAG/SPI Selection header	1–2 (SPI), 2–3 (JTAG)
J53	FTDI Mode selection	1–2 (Normal), 2–3 (Reset)
J54	ispClock 5406 reference clock selector	1–2 (External), 2–3 (Internal)
J55	ECP5 Bank 2 voltage selection	1–2 (3V3), 2–3 (2V5), 2–4 (CN1/CN2_VCC)
SW1	Global reset	—
SW2	Power on switch	—
SW3	General purpose DIP switches	—
SW4	Program reset for program	—

3. Programming Circuit

The Mini-B USB connector is used for programming the board with Lattice Diamond® Programmer software. The Mini-B USB connector (J2) interfaces to the FTDI FT2232H IC. The FTDI IC works with Diamond programmer software to provide interfaces for:

- JTAG – to program LFE5UM-85F, ispClock, and SPI Flash (ECP5 in MSPI Mode)
- SPI – to program external devices connected to the ECP5 VIP processor board

Figure 3.1 shows the programming block of ECP5 VIP processor board. Table 3.1 shows the SPI Flash.

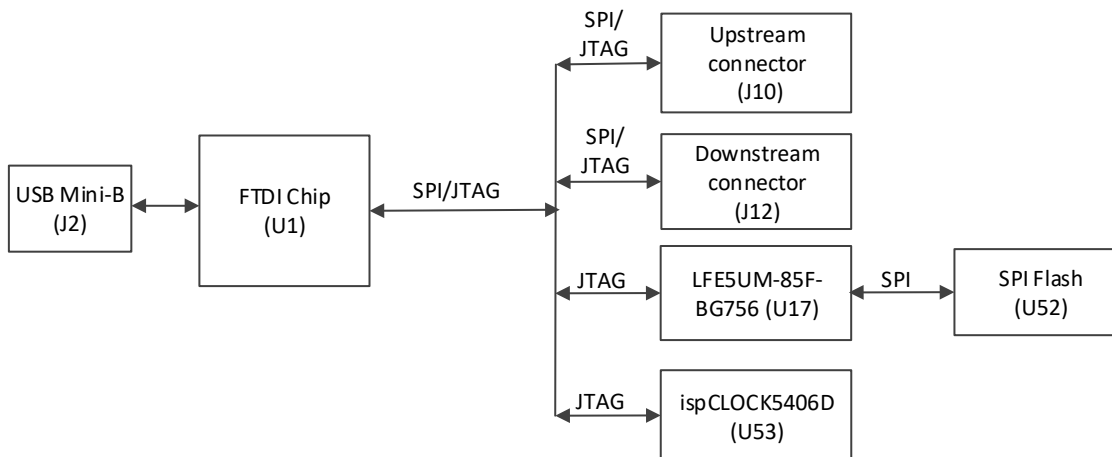


Figure 3.1. Programming Block using USB Interface

Table 3.1. SPI Flash Memory

Board Revision	Family	Device
B	Micron	N25Q128A
C	Macronix	MX25L1283

4. ECP5 Interface Support

The ECP5 VIP processor board supports various onboard interfaces and external interfaces through board-to-board connectors. The sections below describe key onboard interfaces supported on ECP5 VIP processor board.

4.1. Clock Interface

Clocking for the ECP5 device on the ECP5 VIP processor board can be done through one of the onboard fixed frequency crystal oscillators and the internal OSC built inside the ECP5 device. The board has 100 MHz fixed frequency OSC to support DDR3 Memory controller and 27 MHz to support MIPI/LVDS related interfaces.

4.2. DDR3 Interface

Figure 4.1 shows the block diagram of the DDR3 Interface. The LFE5UM-85F-BG756 device DDR3 memory controller is used to interface with the onboard DDR3 memory devices and supports a single rank and multiple memory devices connected on the board.

Each memory device supports 16-bit parallel data with 1 Gb memory capacity. The combined capacity supported is 2 Gb. The DDR3 memory controller can be configured to support either 32-bit or 16-bit wide memory interface by enabling the chip select signals for both memory devices. This board is designed to support both on-board VTT termination as well as on-die termination, which can be configured by the memory controller. For a 16-bit wide memory interface, both Bank 7 and Bank 8 need to support SSTL15 to prevent contention on the shared DDR3 VREF. This is done by including at least one SSTL15 input pin on the unused bank.

Note: Rev B of the ECP5 VIP Processor board only supports 16-bit data width. To support 32-bit data width on the Rev B board, CKE of the DDR controller should be connected to both DDR3_CE0 and DDR3_CE1 on the board, or use the Rev C board.

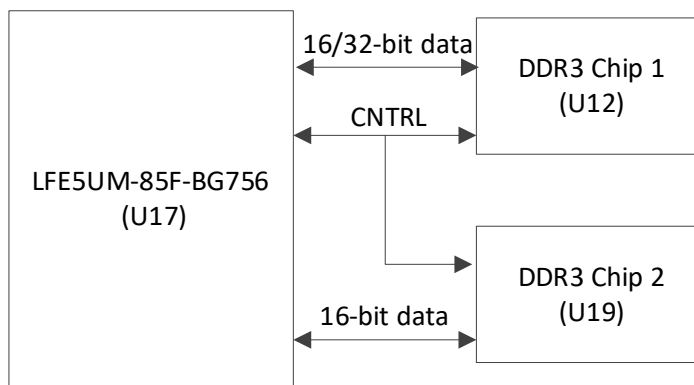


Figure 4.1. DDR3 Interface

4.3. Nanovesta Interface

Figure 4.2 shows the block diagram of the Nanovesta connector interface. The LFE5UM-85F-BG756 (U17) device receives camera input from the Nanovesta connectors. Pin mapping of the Nanovesta connector interface is designed such that the legacy Lattice Nanovesta camera sensor boards can be interfaced with ECP5 VIP processor board. It supports both parallel and SLVS interface for receiving camera input from sensor module.

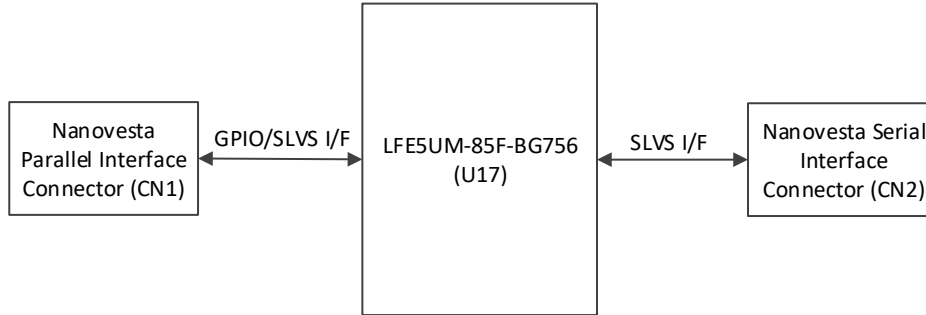


Figure 4.2. Nanovesta Connector Interface

4.4. Upstream and Downstream interface

Figure 4.3 shows the block diagram of the Upstream and Downstream connector. Upstream and Downstream connectors are used to interface the ECP5 VIP processor board to any other external boards for bridging applications. These connectors support multiple interfaces, such as LVDS, MIPI, SPI, JTAG, SerDes, and general purpose interface.

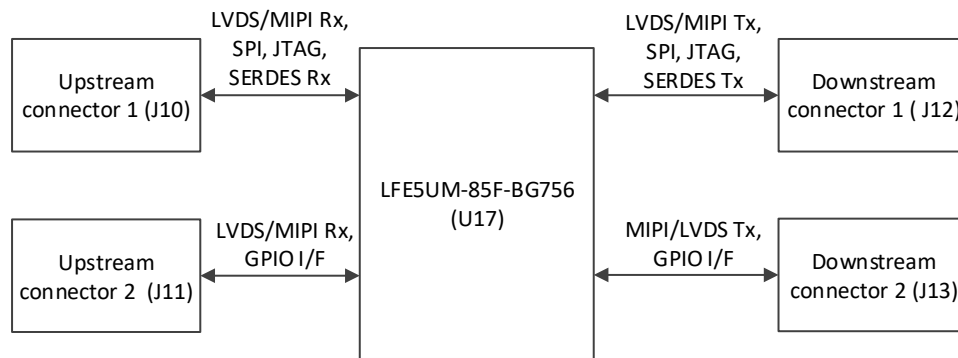


Figure 4.3. Upstream and Downstream Connector

4.5. ispClock5406D Interface

Figure 4.4 shows the block diagram of the ispClock5406D interface. For more information on Lattice ispClock, visit www.latticesemi.com/ispclock.

The ispClock5406D device can be programmed using JTAG through FTDI interface. This circuitry is used as a reference clock generation circuit for the ECP5 SerDes interface. The input clock source for the reference clock generation circuit can be onboard oscillator or the PLL output from ECP5 FPGA. Jumper J54 (Ref_Sel) can be used to select the input of the ispClock5406D.

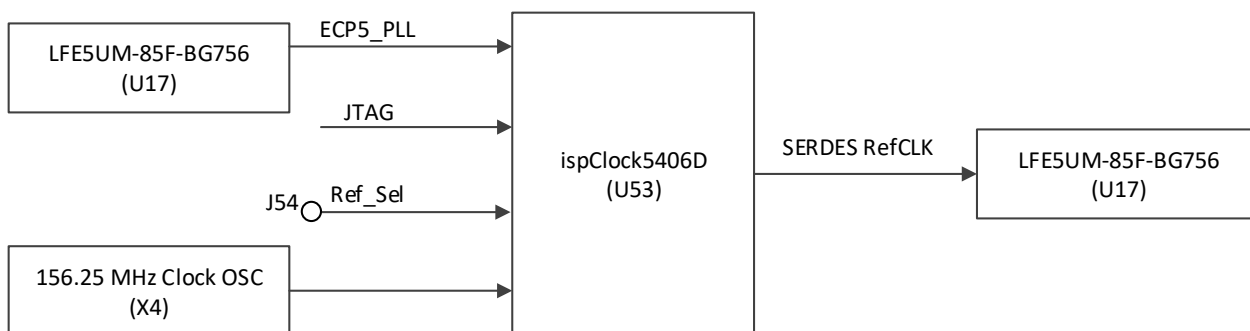


Figure 4.4. ispClock5406D Interface

4.6. Debugging Interface

The ECP5 VIP processor board supports onboard debugging in the form of JTAG, GPIO Headers and onboard DIP switches. Table 4.1 to Table 4.3 list the ECP5 ball mapping for the debugging interfaces.

Table 4.1. Header (J14)

Header (J14) Pin Number	Net Name	ECP5 Ball number
1	Header5	AK31
2	VCCIO4	—
3	Header6	AJ31
4	Header1	AK32
5	Header7	AM31
6	Header2	AJ32
7	Header8	AL32
8	Header3	AM30
9	GND	—
10	Header4	AL30

Table 4.2. Switch (SW3)

Switch (SW3) Pin Number	Net Name	ECP5 Ball Number
1	SW1	B26
2	SW2	C26
3	SW3	D26
4	SW4	A28
5	SW5	A29
6	SW6	A30
7	SW7	A31
8	SW8	B28

Table 4.3. JTAG Connector (J1)

JTAG Connector (J1) Pin Number	Net Name
1	3V3
2	FTDI_TDO
3	FTDI_TDI
4	NC
5	NC
6	FTDI_TMS
7	GND
8	FTDI_TCK

5. Power Supply

The power supply to the development kit is provided from an external 12 V DC adaptor. Figure 5.1 shows the power supply block of the ECP5 VIP processor board. The Mini-B USB connector is used only for programming and the external power adaptor must be connected to source power for the on-board regulators for the normal operation and successful programming.

The external adaptor provides 12 V power source through voltage regulators on the board as well as to the external boards connected to Nanovesta, upstream and downstream connectors. Each I/O bank voltage can be selected by using jumpers, see Table 2.1 for the voltage selection. All voltage generation from the onboard regulator can be measured by a respective test point on the board.

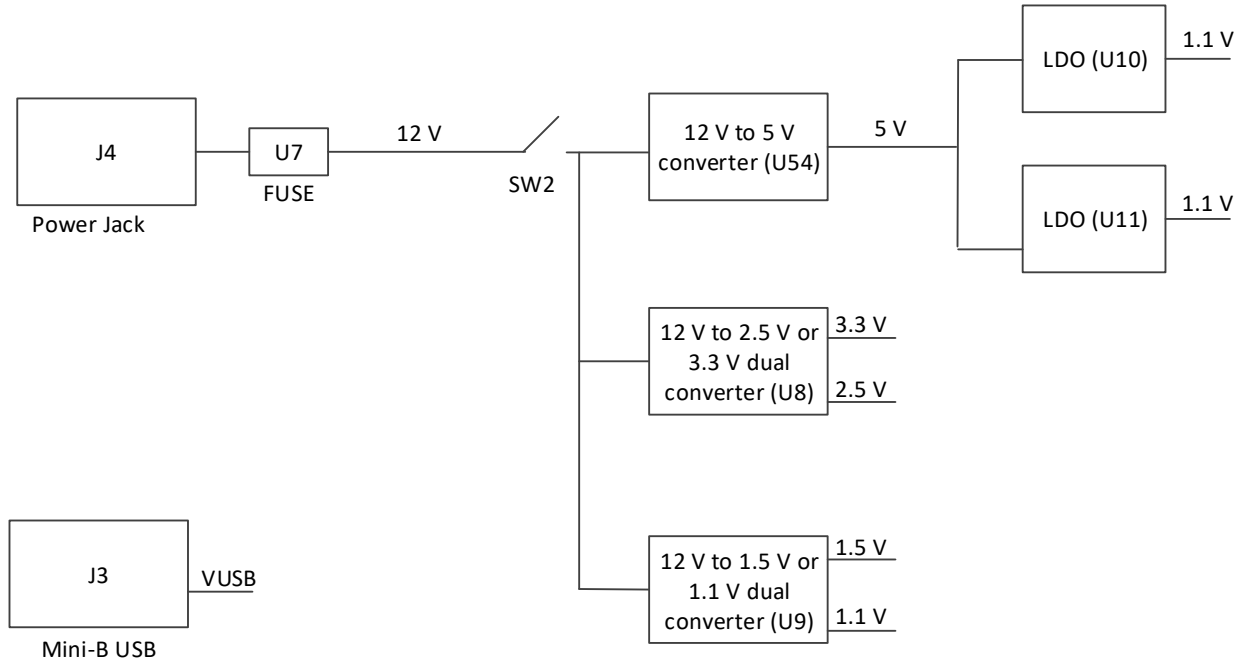


Figure 5.1. Power Supply Block

Table 5.1 lists the device power rails. There are five voltage regulators on the board used to supply the 5 V, 3.3 V, 2.5 V, 1.5 V, and 1.1 V rails. The input to these regulators is either the external 12 V adaptor or on-board regulators that are connected to the board. Switch SW2 is used to connect or disconnect the external adaptor power to the board.

Table 5.1. Device Power Rail Summary

Voltage Rail	Source Rail	Test Points	Voltage on Net (V)	Status LED	LED Color
12 V	12_Ext	—	12	D15	Green
5 V	12 V	5V	5	D23	Green
3V3	12 V	3V3	3.3	D17	Green
2V5	12 V	2V5	2.5	D14	Green
1V5	12 V	1V5	1.5	D16	Green
VCC_CORE	12 V	VCC_CORE	1.1	D18	Green
VCCHTX	5 V	VCCHTX	1.1	D20	Green
VCCA	5 V	VCCA	1.1	D19	Green

6. ECP5 I/O Ball Mapping to Connectors

Table 6.1. Upstream Connector Mapping

J10			J11		
Pin number on Connector	Net Name	ECP5 Ball	Pin Number on Connector	Net Name	ECP5 Ball
1	3V3	—	1	3V3	—
2	5V	—	2	3V3	—
3	3V3	—	3	3V3	—
4	5V	—	4	3V3	—
5	GND	—	5	UP_GPIO9	F29
6	5V	—	6	UP_GPIO17	A13
7	LVDS_CP	P27	7	UP_GPIO10	F28
8	GND	—	8	UP_GPIO18	A8
9	LVDS_CN	P26	9	UP_GPIO1	C29
10	LVDS_D2P	J30	10	UP_GPIO19	F9
11	GND	—	11	UP_GPIO2	C30
12	LVDS_D2N	K30	12	UP_GPIO20	D9
13	LVDS_D0P	D30	13	LDI_RX_D3_P	F32
14	GND	—	14	UP_GPIO21	C9
15	LVDS_D0N	D31	15	LDI_RX_D3_N	H32
16	LVDS_D3P	L31	16	UP_GPIO22	A9
17	GND	—	17	GND	—
18	LVDS_D3N	L30	18	GND	—
19	LVDS_D1P	K32	19	GND	—
20	GND	—	20	GND	—
21	LVDS_D1N	L32	21	LDI_RX_D2_P	J29
22	2V5	—	22	GND	—
23	GND	—	23	LDI_RX_D2_N	K29
24	2V5	—	24	UP_GPIO25	C10
25	DIR_GPIO3	—	25	UP_GPIO33	D13
26	GND	—	26	UP_GPIO26	B10
27	UP_MCLK	—	27	UP_GPIO34	C13
28	GSRN	AH1	28	UP_GPIO27	A10
29	UP_SISPI	—	29	LDI_RX_D0_P	K27
30	UP_GPIO48	C16	30	UP_GPIO28	E11
31	UP_SISO	—	31	LDI_RX_D0_N	K26
32	UP_GPIO49	B16	32	UP_GPIO29	D11
33	UP_CSSPIN	—	33	GND	—
34	GND	—	34	UP_GPIO30	C11
35	UP_CDONE	—	35	GND	—
36	HDRXPO_D1CH0	AM17	36	GND	—
37	UP_CRESETB	—	37	LDI_RX_D1_P	J26
38	HDRXNO_D1CH0	AM18	38	GND	—
39	DIR_GPIO4	—	39	LDI_RX_D1_N	J27
40	GND	—	40	GND	—
41	SCL	AG1	41	UP_GPIO31	B11
42	HDRXPO_D1CH1	AM20	42	UP_GPIO39	B14

J10			J11		
Pin number on Connector	Net Name	ECP5 Ball	Pin Number on Connector	Net Name	ECP5 Ball
43	SDA	AJ1	43	UP_GPIO32	F13
44	HDRXNO_D1CH1	AM21	44	UP_GPIO40	A14
45	FTDI_TCK	AK5	45	UP_GPIO37	D14
46	GND	—	46	UP_GPIO41	B4
47	FTDI_TDO	—	47	UP_GPIO38	C14
48	HDRXPO_DOCH0	AM8	48	UP_GPIO42	F15
49	FTDI_TDI	—	49	UP_GPIO45	A15
50	HDRXNO_DOCH0	AM9	50	UP_GPIO43	D15
51	FTDI_TMS	AM5	51	UP_GPIO50	D17
52	GND	—	52	UP_GPIO44	C15
53	DIR_GPIO5	—	53	GND	—
54	HDRXPO_DOCH1	AM11	54	GND	—
55	GND	—	55	GND	—
56	HDRXNO_DOCH1	AM12	56	GND	—
57	GND	—	57	2V5	—
58	GND	—	58	2V5	—
59	GND	—	59	2V5	—
60	DIR_GPIO1	—	60	2V5	—

Table 6.2. Downstream Connector Pin Mapping

J12			J13		
Pin number on Connector	Net Name	ECP5 Ball	Pin number on Connector	Net Name	ECP5 Ball
1	GND	—	1	3V3	—
2	12V	—	2	3V3	—
3	MIPITX_CLKP	A18	3	3V3	—
4	12V	—	4	3V3	—
5	MIPITX_CLKN	C18	5	LDI_TX_D0_P	W31
6	12V	—	6	LDI_TX_D1_P	AB30
7	GND	—	7	LDI_TX_D0_N	Y32
8	12V	—	8	LDI_TX_D1_N	AB29
9	MIPITX_DATA0P	F18, R27	9	LDI_TX_D3_P	R32
10	MIPITX_DATA2P	D19, U29	10	LDI_TX_D2_P	AD27
11	MIPITX_DATA0N	A19, T27	11	LDI_TX_D3_N	T31
12	MIPITX_DATA2N	E19, V29	12	LDI_TX_D2_N	AE27
13	GND	—	13	DW_GPIO5	T29
14	GND	—	14	DW_GPIO27	AB28
15	MIPITX_DATA1P	B19, R29	15	DW_GPIO6	U28
16	MIPITX_DATA3P	F19, P31	16	DW_GPIO28	AB27
17	MIPITX_DATA1N	C19, T28	17	DW_GPIO7	V27
18	MIPITX_DATA3N	P30, A20	18	DW_GPIO29	AC26
19	GND	—	19	DW_GPIO8	V26
20	GND	—	20	GND	—
21	DW_GPIO46	A25	21	GND	—

J12			J13		
Pin number on Connector	Net Name	ECP5 Ball	Pin number on Connector	Net Name	ECP5 Ball
22	DW_GPIO48	D25	22	DW_GPIO30	AD26
23	DW_GPIO47	C25	23	DW_GPIO44	C24
24	DW_GPIO49	E25	24	DW_GPIO23	Y27
25	DIR_GPIO3	—	25	DW_GPIO45	D24
26	GND	—	26	DW_GPIO24	W28
27	ECP_SCLK	AM3	27	DW_GPIO11	P32
28	GSRN	AH1	28	DW_GPIO33	AE29
29	ECP_MOSI	AK2	29	DW_GPIO12	U31
30	DW_GPIO50	F25	30	DW_GPIO25	Y29
31	ECP_MISO	AJ2	31	DW_GPIO3	U27
32	DW_GPIO51	F17	32	DW_GPIO26	W29
33	FPGA_CSN	AG3	33	DW_GPIO4	U26
34	GND	—	34	DW_GPIO36	AC28
35	DW_DONE	AJ4	35	DW_GPIO15	W30
36	HDTXPO_DOCH0	AK9	36	DW_GPIO1	T30
37	DW_INITN	AG4	37	DW_GPIO16	Y30
38	HDTXNO_DOCH0	AK10	38	DW_GPIO2	N32
39	DIR_GPIO4	—	39	GND	—
40	GND	—	40	GND	—
41	SCL	AG1	41	DW_GPIO17	T32
42	HDTXPO_DOCH1	AK12	42	DW_GPIO39	AC31
43	SDA	AJ1	43	DW_GPIO18	AC30
44	HDTXNO_DOCH1	AK13	44	DW_GPIO40	AB32
45	FTDI_TCK	AK5	45	DW_GPIO19	AB31
46	GND	—	46	DW_GPIO41	AC32
47	FTDI_TDO	—	47	DW_GPIO20	V32
48	HDTXPO_D1CH0	AK18	48	DW_GPIO42	AD32
49	FTDI_TDI	—	49	DW_GPIO21	W32
50	HDTXNO_D1CH0	AK19	50	DW_GPIO43	A24
51	FTDI_TMS	AM5	51	DW_GPIO22	Y26
52	GND	—	52	LDI_TX_CK_P	R26
53	DIR_GPIO5	—	53	GND	—
54	HDTXPO_D1CH1	AK21	54	LDI_TX_CK_N	T26
55	GND	—	55	GND	—
56	HDTXNO_D1CH1	AK22	56	GND	—
57	VCCHTX	—	57	2V5	—
58	GND	—	58	2V5	—
59	VCCHTX	—	59	2V5	—
60	DIR_GPIO1	—	60	2V5	—

Table 6.3. Nanovesta Connector Pin Mapping

Connector 1 (CN2) Top - High SPI to Sensor			Connector 1 (CN1) Top - Parallel up to Sensor1		
Pin number on Connector	Net Name	ECP5 Ball	Pin number on Connector	Net Name	ECP5 Ball
1	5V	—	1	5V	—
2	5V	—	2	5V	—
3	CN2_VCC	—	3	CN1_VCC	—
4	VDDIO_RP	—	4	VDDIO_RH	A16
5	GND	—	5	GND	—
6	GND	—	6	GND	—
7	GND	—	7	GND	—
8	GND	—	8	GND	—
9	—	—	9	EXTCLK_FPGA	B17
10	HISPI_RESETN	C8	10	PIXCLK	C17
11	SLVS_3N	E30	11	LINE_VALID	A4
12	SLVS_5N	N29	12	FRAME_VALID	A5
13	SLVS_3P	F30	13	DOUT6	F11
14	SLVS_5P	N30	14	DOUT4	E10
15	PANASONIC_B1N	H30	15	SLVS_6N	D32
16	SLVS_CN	N26	16	SLVS_8N	H28
17	PANASONIC_B1P	H31	17	SLVS_6P	C32
18	SLVS_CP	N27	18	SLVS_8P	H27
19	SLVS_2N	C31	19	SLVS_7N	L29
20	PANASONIC_B0N	J32	20	SLVS_9N	L27
21	SLVS_2P	B32	21	SLVS_7P	K28
22	PANASONIC_B0P	K31	22	SLVS_9P	L26
23	SLVS_4N	E32	23	DOUT11	F14
24	SLVS_0N	D28	24	DOUT9	A11
25	SLVS_4P	F31	25	SIGNAL_TRIGGER	D7
26	SLVS_0P	C28	26	SADDR	F8
27	SLVS_1N	E29	27	RESET_BAR	C7
28	RESERVED	B8	28	SDCLK	E8
29	SLVS_1P	D29	29	OUTPUT_EN_BAR	B7
30	HISPI_SDA	A2	30	SDATA	D8
31	—	—	31	STANDBY	A7
32	HISPI_SCLK	A3	32	OSC_EN	B3
33	GND	—	33	GND	—
34	GND	—	34	GND	—
35	GND	—	35	GND	—
36	GND	—	36	GND	—
37	CN2_VCC	—	37	CN1_VCC	—
38	CN2_VCC	—	38	CN1_VCC	—
39	5V	—	39	5V	—
40	5V	—	40	5V	—
SHIELD1	5V	—	SHIELD1	5V	—
SHIELD2	5V	—	SHIELD2	5V	—

7. Status Indicators

The LED status indicators on the board show power, configuration, and application status. [Table 7.1](#) lists the status LED I/O map.

Table 7.1. Status LED I/O Map

Device	LED	Net Name	Color
LFE5UM-85F-BG756	D24	LED1	Green
LFE5UM-85F-BG756	D25	LED2	Green
LFE5UM-85F-BG756	D26	LED3	Green
LFE5UM-85F-BG756	D27	LED4	Green
LFE5UM-85F-BG756	D28	LED5	Green
LFE5UM-85F-BG756	D29	LED6	Green
LFE5UM-85F-BG756	D30	LED7	Green
LFE5UM-85F-BG756	D31	LED8	Green
ispClock5406D	D21	—	Blue
LFE5UM-85F-BG756	D3	FPGA_CSN	Blue
LFE5UM-85F-BG756	D4	FPGA_CSN1	Blue
LFE5UM-85F-BG756	D1	DW_INITN	Blue
LFE5UM-85F-BG756	D2	DW_DONE	Green

8. Ordering Information

This board is included as part of a kit, and not available as a separate item. The below part number is for reference only, so it is clear which board is described in this document. Visit www.latticesemi.com/boards for the latest ordering information.

Table 8.1. Reference Part Number

Description	Ordering Part Number
ECP5 VIP Processor Board	LFE5-VIP-P-EVN

Appendix A. ECP5 VIP Processor Board Schematics

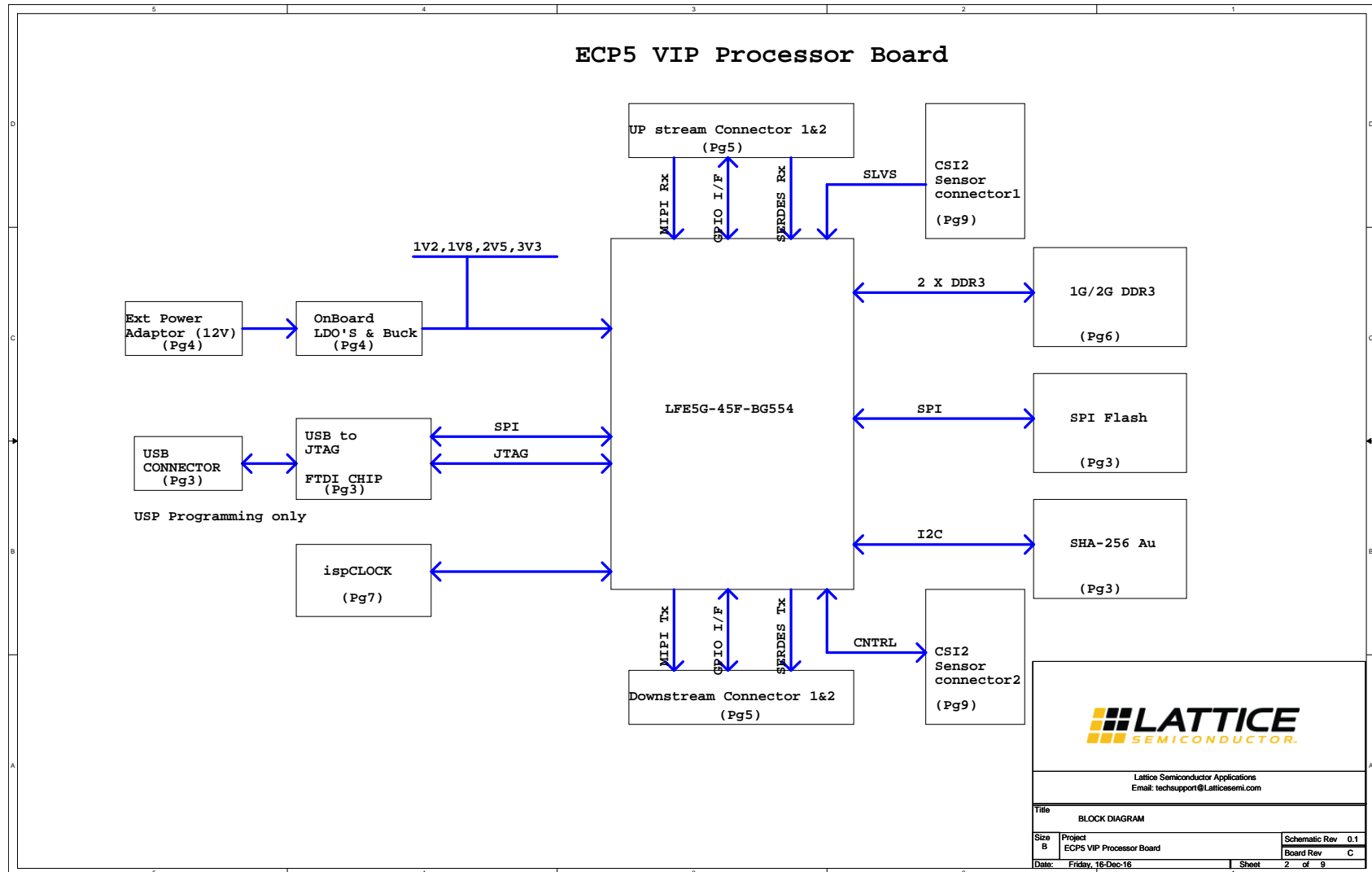


Figure A.1. Block Diagram

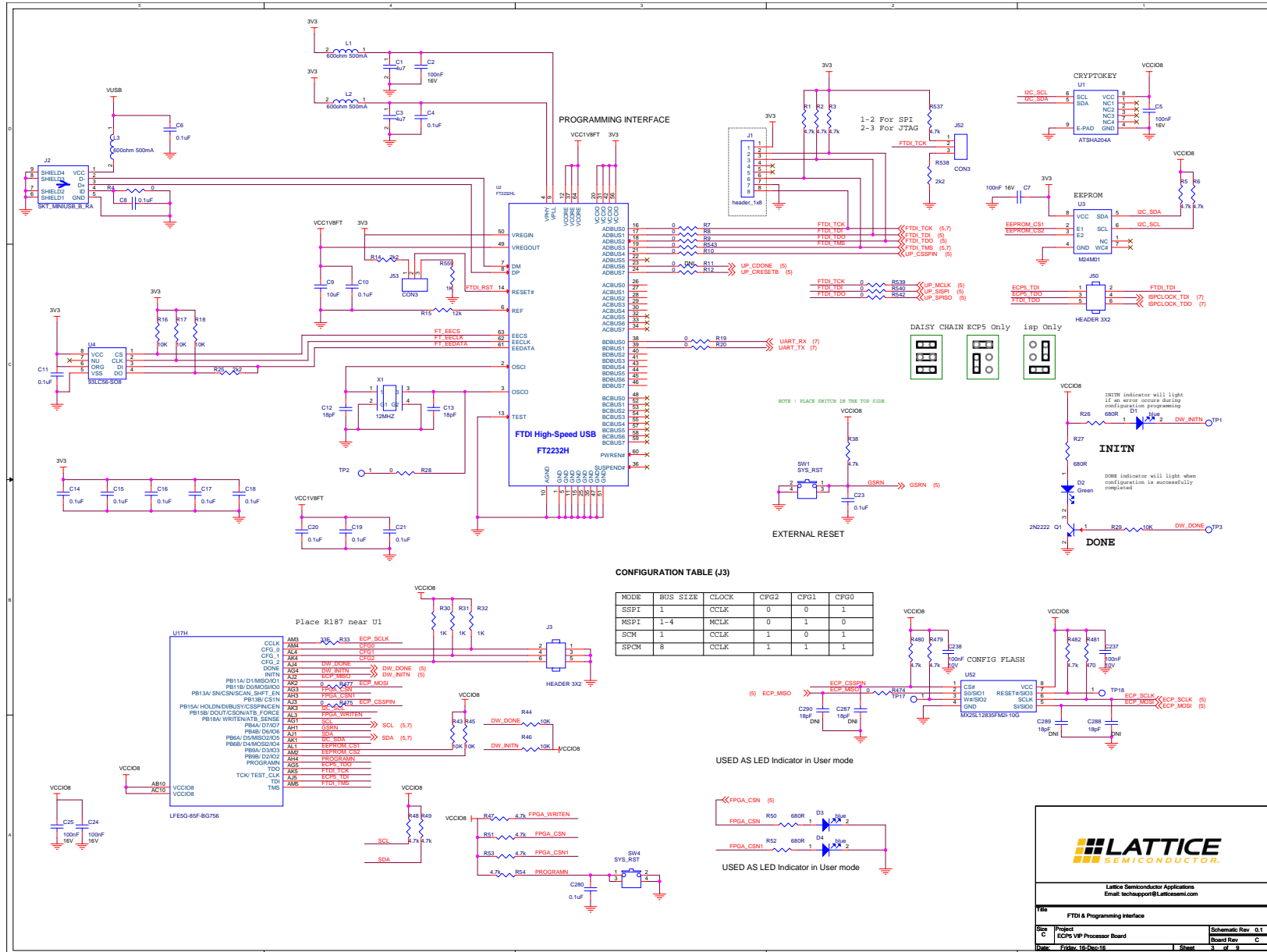


Figure A.2. FTDI and Programming Interface

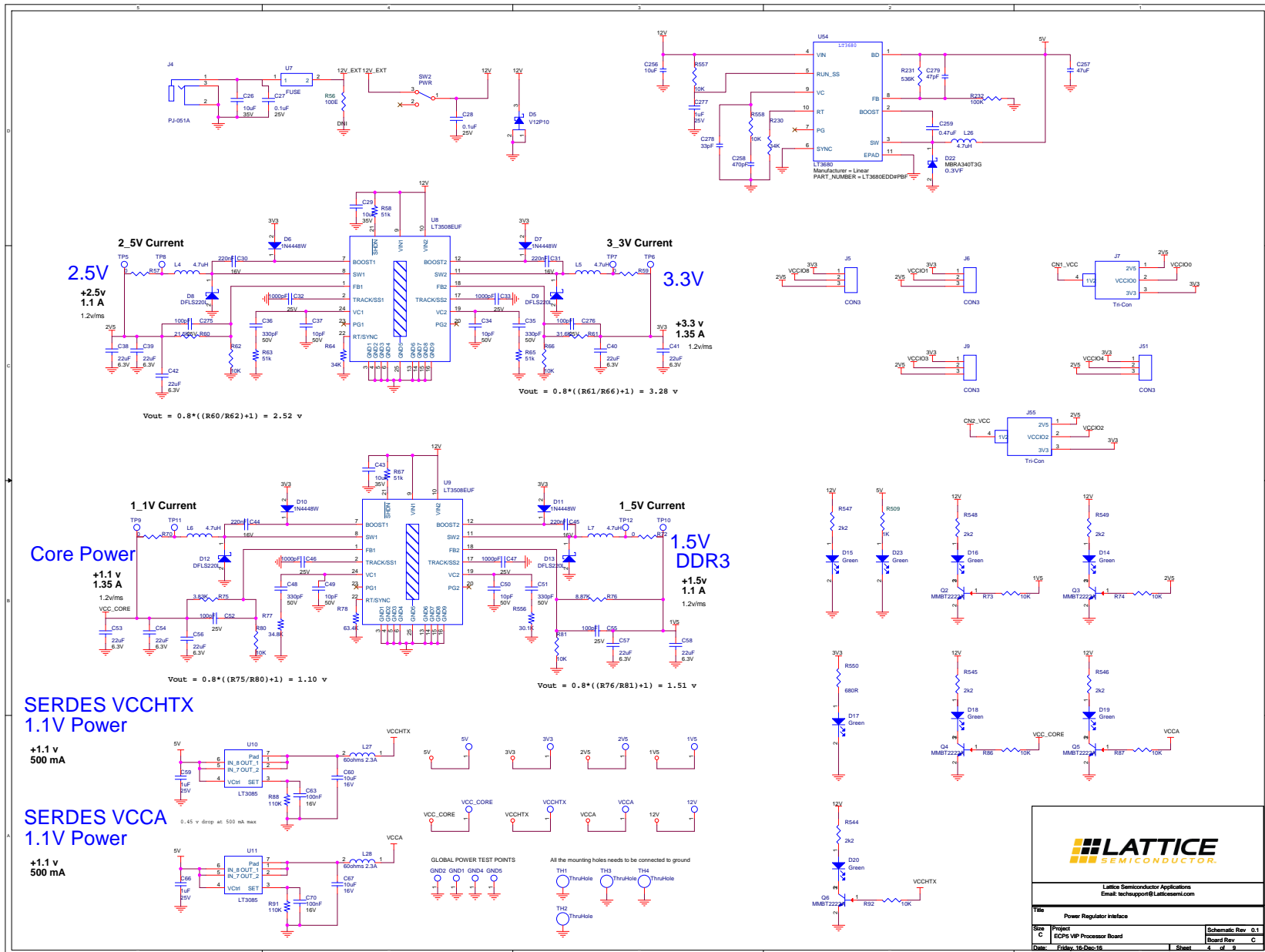


Figure A.3. Power Regulator Interface

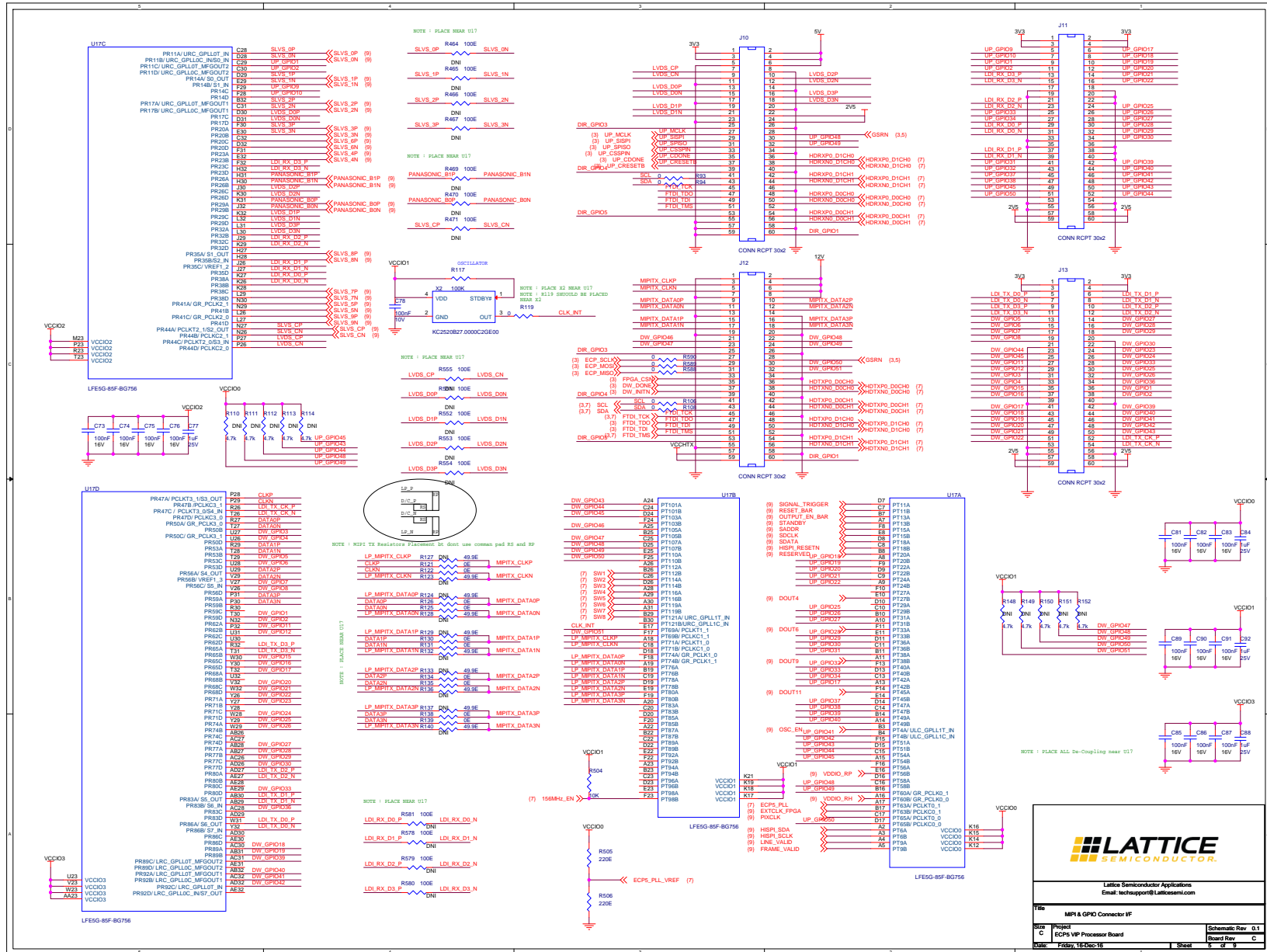


Figure A.4. MIPI and GPIO Connector Interface

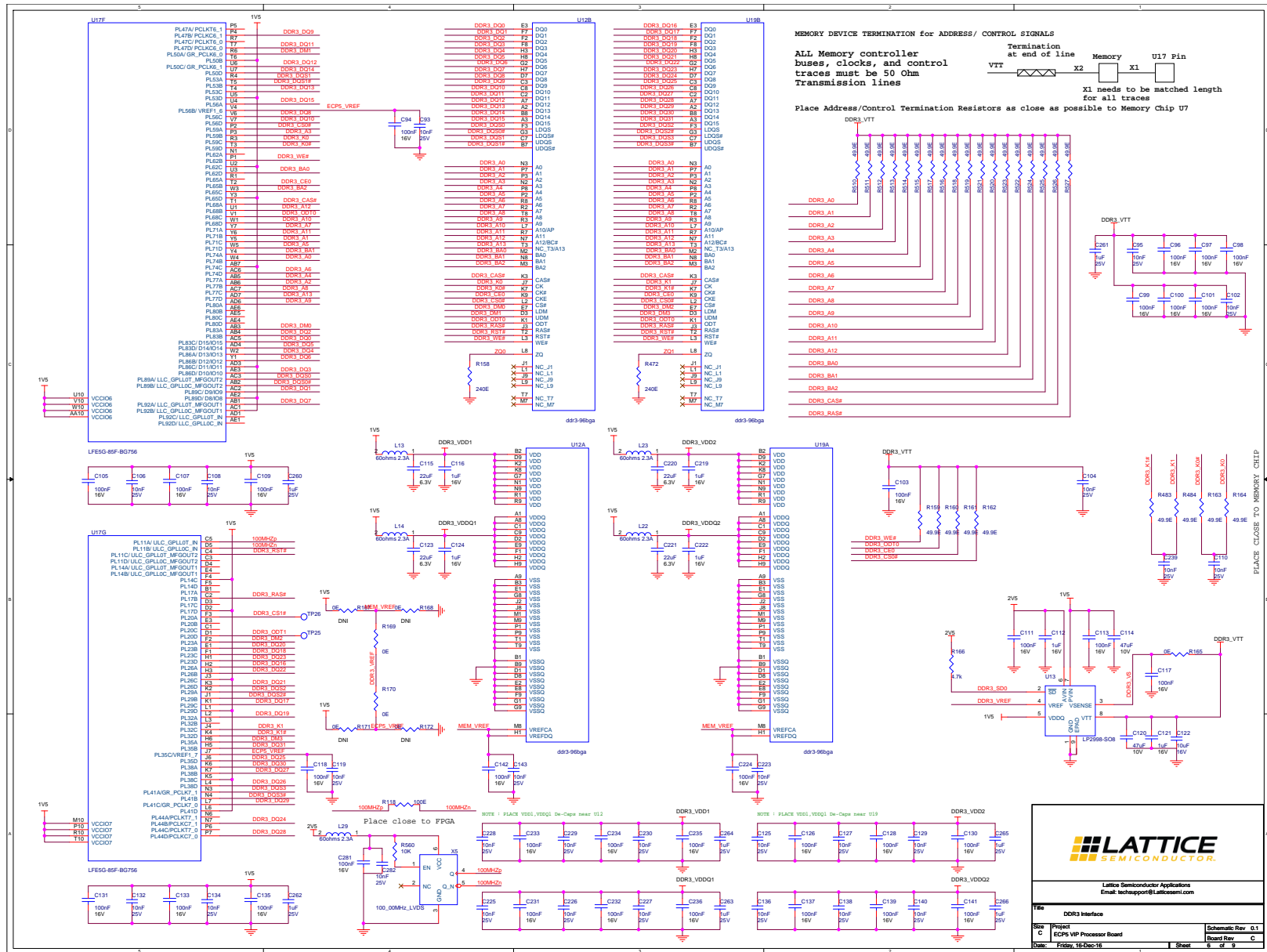
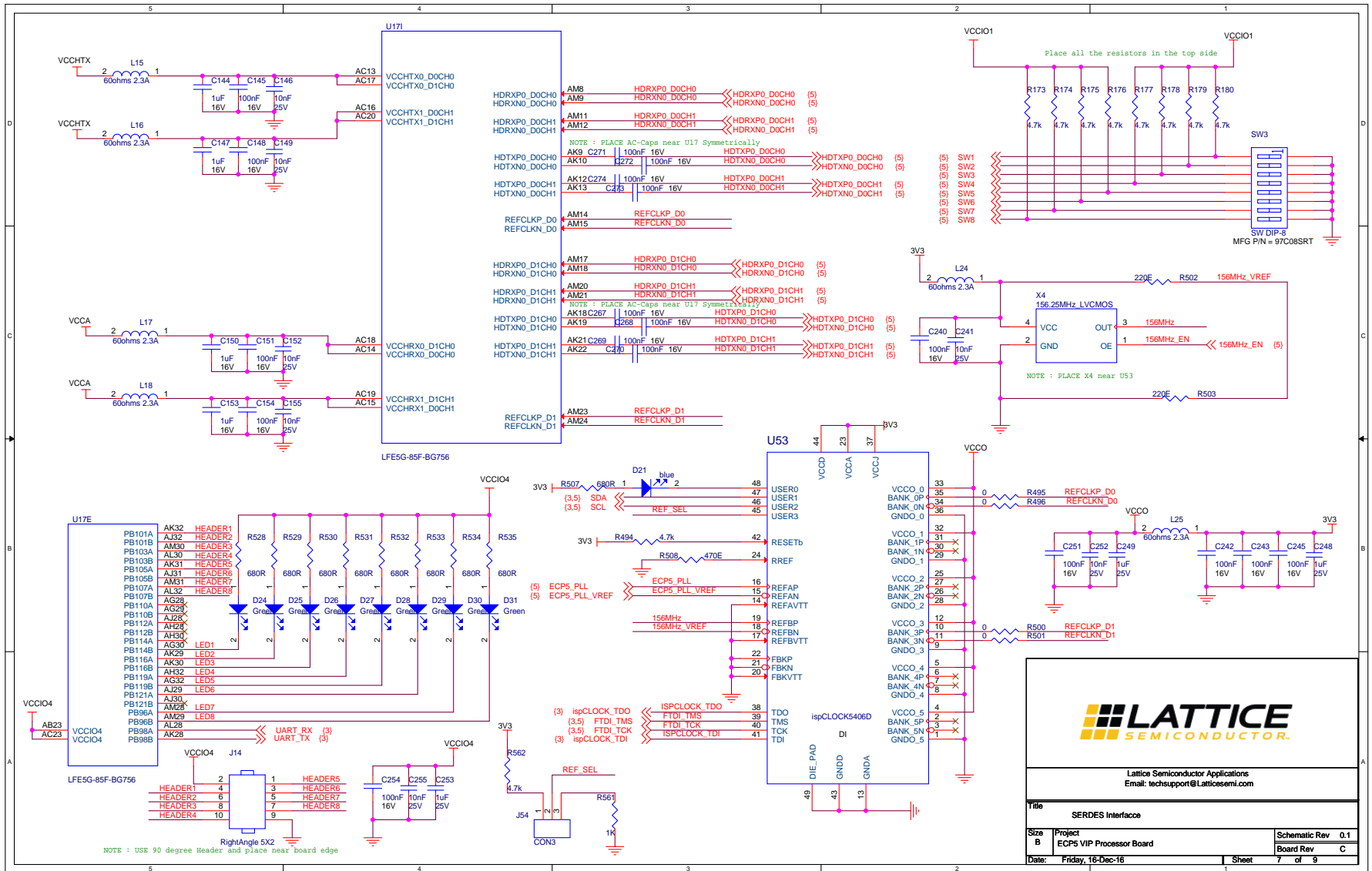


Figure A.5. DDR3 Interface



Lattice Semiconductor Applications
Email: techsupport@Latticesemi.com

Title: SERDES Interface		
Size B	Project: ECP5 VIP Processor Board	Schematic Rev: 0.1
Date: Friday, 16-Dec-16	Sheet: 7 of 9	Board Rev: C

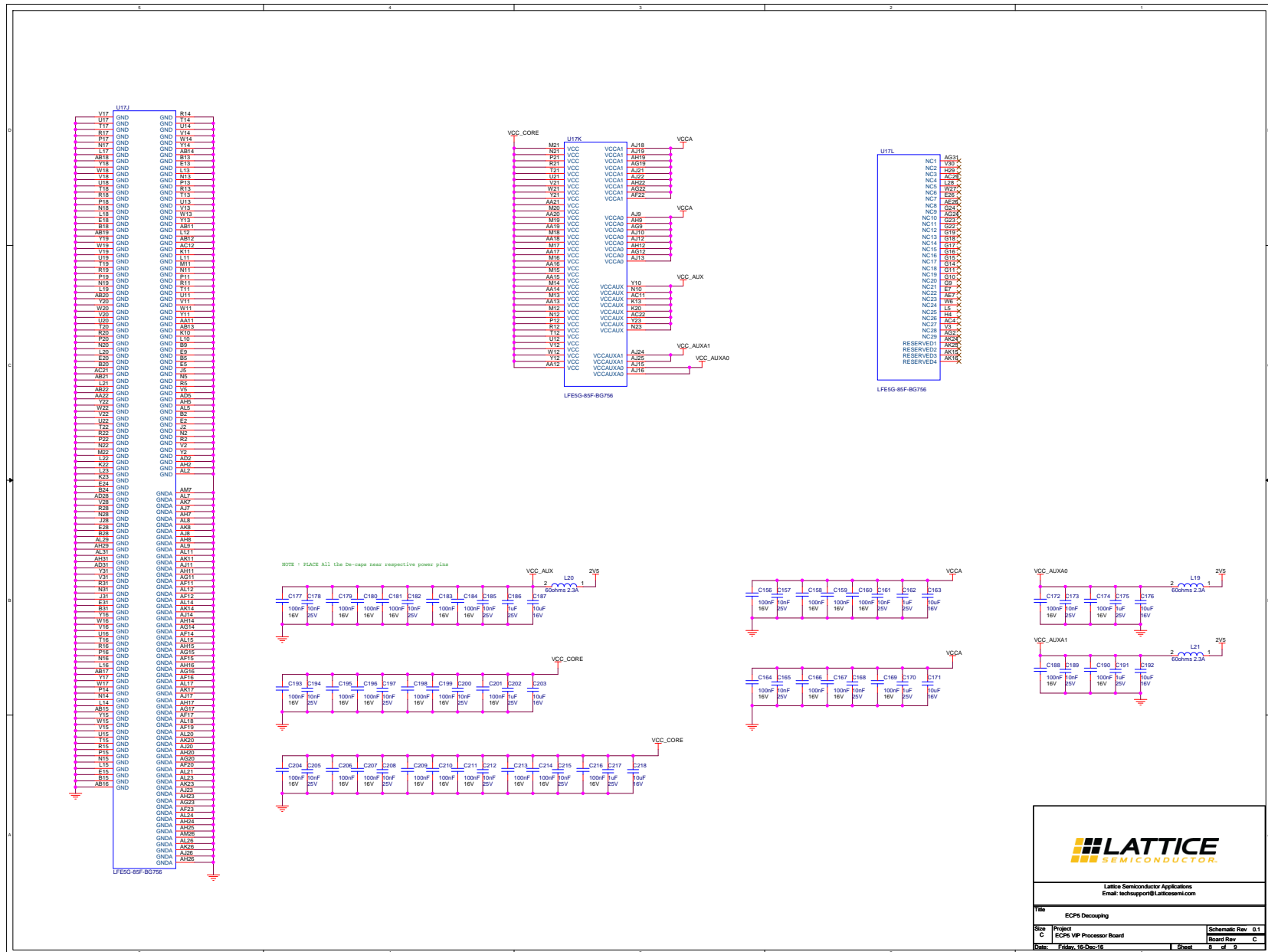


Figure A.7. ECP5 Decoupling

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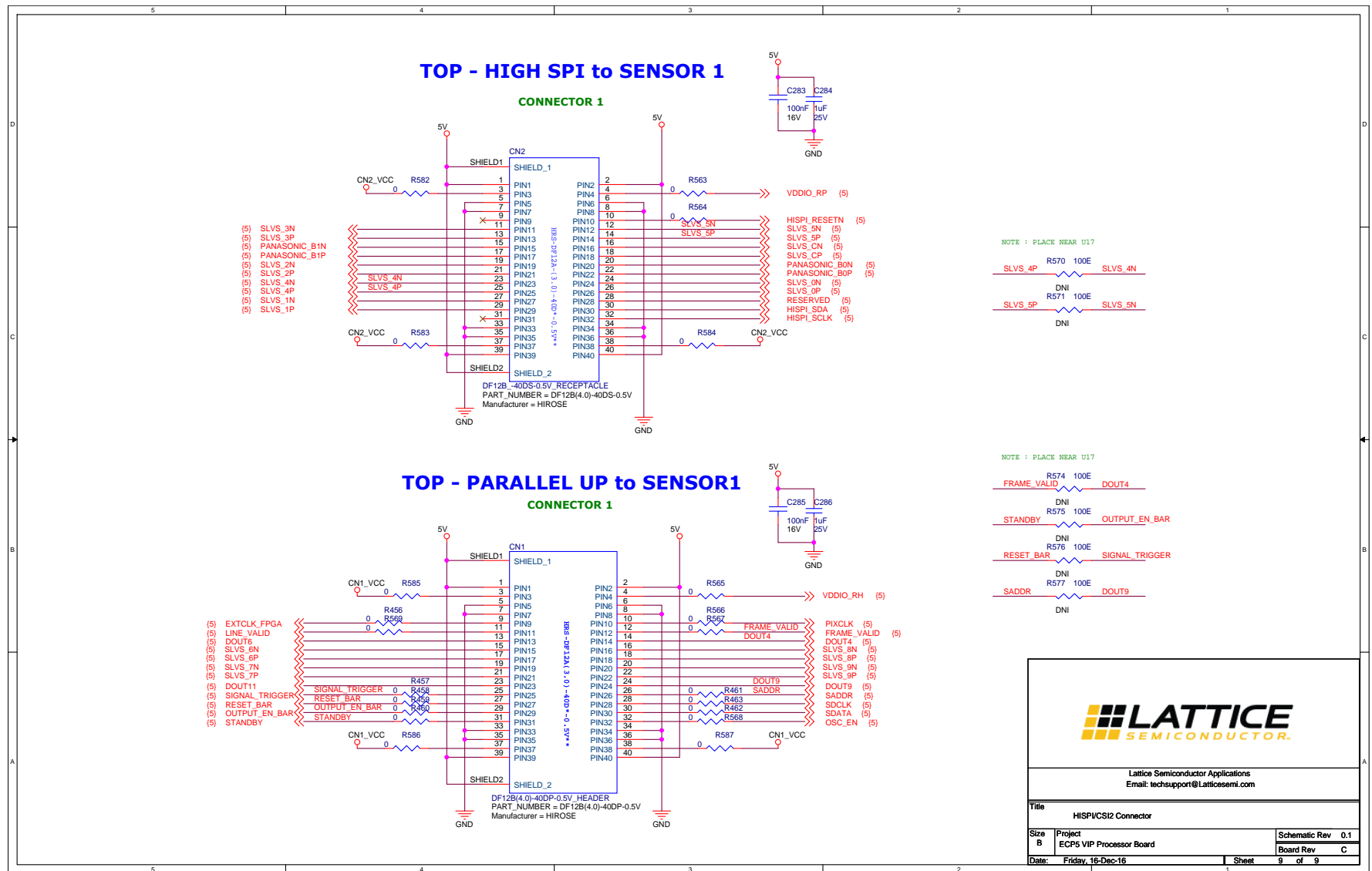


Figure A.8. HISPI/CSI2 Connector

Lattice Semiconductor Applications
Email: techsupport@Latticesemi.com

Title		HISPI/CSI2 Connector	
Size	Project	Schematic Rev	
B	ECP5 VIP Processor Board	0.1	
Date: Friday, 16-Dec-16		Board Rev	C
		Sheet	9 of 9

Appendix B. ECP5 VIP Processor Board Bill of Materials

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
1	CN1	1	DF12B(4.0)-40DP-0.5V_HEADER	HRS-DF12B-HEADER	—	DF12B(4.0)-40DP-0.5V	Hirose	CONN HEADER 40POS 4 mm SMD 0.5 mm
2	CN2	1	DF12B_-40DS-0.5V_RECEPTACLE	HRS-DF12B-RECEPTACLE-CENTER	—	DF12B(4.0)-40DS-0.5V	Hirose	CONN RECEPT 40POS 0.5 mm GOLD SMD
3	C1, C3	2	4u7	C0603	—	885012106005	Würth	CAP CER 4.7 µF 6.3 V X5R 0603
4	C2, C5, C7, C24, C25, C73, C74, C75, C76, C78, C81, C82, C83, C85, C86, C87, C89, C90, C91, C94, C96, C97, C98, C99, C100, C101, C103, C105, C107, C109, C111, C113, C117, C118, C126, C128, C130, C131, C133, C135, C137, C139, C141, C142, C145, C148, C151, C154, C156, C158, C159, C160, C164, C166, C167, C169, C172, C174, C177, C179, C180, C181, C183, C184, C188, C190, C193, C195, C196, C198, C199, C201, C204, C206, C207, C209, C210, C211, C213, C214, C216, C224, C231, C232, C233, C234, C235, C236, C237, C238, C240, C242, C243, C245, C251, C254, C281, C283, C285	99	100nF	C0201	—	CC0201KRX5R7BB104	Yageo	CAP CER 0.1 µF 16 V X5R 0201
5	C4, C10, C11, C14, C15, C16, C17, C18, C19, C20, C21	11	0.1uF	C0201	—	CC0201KRX5R7BB104	Yageo	CAP CER 0.1 µF 16 V X5R 0201
6	C6, C8, C23, C280	4	0.1uF	C0402	—	885012205037	Würth	CAP CER 0.1 µF 16 V X7R 0402
7	C9	1	10uF	C0603	—	LMK107BJ106MALTD	Taiyo Yuden	CAP CER 10 µF 10 V X5R 20% 0603
8	C12, C13	2	18pF	C0402	—	C0402C180K3GACTU	Kemet	CAP CER 18 pF 25 V COG 0402
9	C26, C29, C43	3	10uF	C6032	—	TRJC106K035RRJ	AVX	Tantalum Capacitors - Solid SMD 10 µF ±10% 35V
10	C27, C28	2	0.1uF	C0603	—	885012206071	Würth	CAP CER 0.1 µF 25 V X7R 0603

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
11	C30, C31, C44, C45	4	220nF	C0402	—	8850121050 17	Wurth	CAP CER 0.22 μ F 16 V X5R 0402
12	C32, C33, C46, C47	4	1000pF	C0402	—	8850122050 44	Wurth	CAP CER 1000 pF 25 V X7R 0402
13	C34, C37, C49, C50	4	10pF	C0402	—	8850120050 55	Wurth	CAP CER 10 pF 50 V NPO 0402
14	C35, C36, C48, C51	4	330pF	C0402	—	8850122050 58	Wurth	CAP CER 330 pF 50 V X7R 0402
15	C38, C39, C40, C41, C42, C53, C54, C56, C57, C58, C115, C123, C220, C221	14	22uF	C0805	—	8850121070 05	Wurth	CAP CER 22 μ F 6.3 V X5R 0805
16	C52, C55, C275, C276	4	100pF	C0402	—	8850120050 46	Wurth	CAP CER 100 pF 25 V NPO 0402
17	C59, C66, C77, C84, C88, C92, C162, C170, C175, C186, C191, C202, C217, C248, C249, C253, C260, C261, C262, C263, C264, C265, C266, C277, C284, C286	26	1uF	C1206	—	THJA105K02 5RJN	AVX	Tantalum Capacitors - Solid SMD 25 V 1 μ F 10%
18	C60, C67, C122, C163, C171, C176, C187, C192, C203, C218	10	10uF	C1210	—	THJB106K01 6SJN	AVX	Tantalum Capacitors - Solid SMD 16 V 10 μ F 10%
19	C63, C70	2	100nF	C0402	—	8850122050 37	Wurth	CAP CER 0.1 μ F 16 V X7R 0402
20	C93, C95, C102, C104, C106, C108, C110, C119, C125, C127, C129, C132, C134, C136, C138, C140, C143, C146, C149, C152, C155, C157, C161, C165, C168, C173, C178, C182, C185, C189, C194, C197, C200, C205, C208, C212, C215, C223, C225, C226, C227, C228, C229, C230, C239, C241, C252, C255, C282	49	10nF	C0201	—	GRM033R61 E103KA12D	Murata	CAP CER 10000 pF 25 V X5R 0201
21	C112, C116, C121, C124, C144, C147, C150, C153, C219, C222	10	1uF	C0805	—	8850122070 51	Wurth	CAP CER 1 μ F 16 V X7R 0805
22	C114, C120	2	47uF	CASEB	—	T491B476K0 10AT	KEMET	CAP TANT 47 μ F 10 V 10% 1411
23	C256	1	10uF	C0603	—	CL10A106M A8NRNC	Samsung	CAP CER 10 μ F 25 V 20% X5R 0603
24	C257	1	47uF	C0805	—	C2012X5R1 A476M125A C	TDK	CAP CER 47 μ F 10 V 20% X5R 0805

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
25	C258	1	470pF	C0603	—	885012006042	Würth Electronics	Multilayer Ceramic Capacitors MLCC - SMD/SMT WCAP-CSGP 470 pF 0603 5% 25 V MLCC
26	C259	1	0.47uF	C0402	—	CL05A474KA5NNNC	Samsung	CAP CER 0.47 µF 25 V 10% X5R 0402
27	C267, C268, C269, C270, C271, C272, C273, C274	8	100nF	C0201	—	CC0201KRX5R7BB104	Yageo	0.10 µF 16 V Ceramic Capacitor X5R 0201 (0603 Metric) 0.024" L x 0.012" W (0.60 mm x 0.30 mm)
28	C278	1	33pF	C0603	—	885012006054	Würth Electronics	Multilayer Ceramic Capacitors MLCC - SMD/SMT WCAP-CSGP 33 pF 0603 5% 50 V MLCC
29	C279	1	47pF	C0402	—	885012005059	Würth Electronics	Multilayer Ceramic Capacitors MLCC - SMD/SMT WCAP-CSGP 47 pF 0402 5% 50 V MLCC
30	C287, C288, C289, C290	4	18pF	C0402	DNL	C0402C180K3GACTU	Kemet	CAP CER 18 pF 25 V COG 0402
31	D1, D3, D4, D21	4	blue	led_0603	—	150060BS75000	Würth	LED BLUE CLEAR 0603 SMD
32	D2, D14, D15, D16, D17, D18, D19, D20, D23, D24, D25, D26, D27, D28, D29, D30, D31	17	Green	led_0603	—	150060VS75000	Würth	LED GREEN CLEAR 0603 SMD
33	D5	1	V12P10	V12P10	—	V12P10-M3/86A	Vishay Intertechnologies	Diode Schottky 100 V 12A 3-Pin(2+Tab) SMPC T/R
34	D6, D7, D10, D11	4	1N4448W	1N4448W	—	1N4448WT	Fairchild Semiconductor	Diode Small Signal Switching 75 V 2-Pin SOD-523F T/R
35	D8, D9, D12, D13	4	DFLS220L	DFLS220L	—	DFLS220L-7	Diodes Incorporated	Diode Schottky 20 V 2 A POWERDI123
36	D22	1	0.3VF	MBRA340T3G	—	MBRA340T3G	On Semiconductor	Diode Schottky 40 V 3 A SMA

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
37	GND1, GND2, GND4, GND5, 5V, 12V, 1V5, 2V5, 3V3, VCC_CORE, VCCHTX, VCCA	12	TP_S_40_63	tp_s_40_63	DNL	—	—	Square test point, 40 mil inner diameter, 63 mil outer diameter
38	J1	1	header_1x8	hdr_amp_8 7220_8_1x 8_100	—	6130081112 1	Würth	8 Positions Header, Unshrouded Connector 0.100" (2.54 mm) Through Hole Gold
39	J2	1	SKT_MINIUSB_B_RA	skt_minibus_b_ra	—	6510051612 1	Würth	CONN COM Type-B Mini USB SMD 5P
40	J3	1	HEADER 3X2	HDR3X2	—	6130062112 1	Würth	6 Positions Header, Unshrouded Connector 0.100" (2.54 mm) Through Hole Gold
41	J4	1	PJ-051A	PJ_051A	—	PJ-051A	CUI Inc.	DC Power Connectors Power Jacks
42	J5, J6, J9, J51	4	CON3	HDR1X3	—	6130031112 1	Würth	3 Positions Header, Unshrouded Connector 0.100" (2.54 mm) Through Hole Gold
43	J7, J55	2	Tri-Con	TriCon	Regular 100mil header	—	—	General 100 mils header
44	J10, J11	2	CONN RCPT 30x2	ERM5-030-050-L-DV-K-TR	—	ERM5-030-050-L-DV-K-TR	Samtec Inc.	Conn High Speed Edge Rate Terminal Strip HDR 60 POS 0.5 mm Solder ST SMD T/R -
45	J12, J13	2	CONN RCPT 30x2	ERF5-030-070-L-DV-K-TR	—	ERF5-030-070-L-DV-K-TR	Samtec Inc.	Conn High Speed Edge Rate Terminal Strip HDR 60 POS 0.5 mm Solder ST SMD T/R -
46	J14	1	RightAngle 5X2	90122-0925	—	90122-0925	Molex	10 Positions Header, Unshrouded, Breakaway Connector 0.100" (2.54 mm) Through Hole, Right Angle Gold
47	J50	1	HEADER 3X2	HDR-3X2	—	6130062112 1	Würth	6 Positions Header, Unshrouded Connector 0.100" (2.54 mm) Through Hole Gold

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
48	J52, J53, J54	3	CON3	HDR_1X3_100MIL	—	61300311121	Würth	3 Positions Header, Unshrouded Connector 0.100" (2.54 mm) Through Hole Gold
49	L1, L2, L3	3	600ohm 500mA	FB0603	—	742792651	Würth	FERRITE BEAD 600 Ω 0603 1LN
50	L4, L5, L6, L7	4	4.7uH	SPD62R	—	SPD62R-472M	API Delevan Inc.	FIXED IND 4.7 μH 2 A 150 MΩ SMD
51	L13, L14, L15, L16, L17, L18, L19, L20, L21, L22, L23, L24, L25, L29	14	60ohms 2.3A	FB0603	—	742792602	Würth	FERRITE BEAD 60 Ω 0603 1LN
52	L26	1	4.7uH	74437346047	—	74437346047	Würth	FIXED IND 4.7 μH 3.8 A 40 MΩ SMD
53	L27, L28	2	60ohms 2.3A	FB0603	—	MPZ1608Y600B	TDK	EMI Filter Beads, Chips & Arrays 60 Ω Power
54	Q1	1	2N2222	MMBT2222 ALT-1	—	MMBT2222 ALT1G	On Semiconductor	Trans GP BJT NPN 40 V 0.6 A Automotive 3-Pin SOT-23 T/R
55	Q2, Q3, Q4, Q5, Q6	5	MMBT2222A	SM_SOT23-3	—	MMBT2222 A,215	NXP USA Inc.	TRANS NPN 40 V 0.6 A SOT23
56	R1, R2, R3, R5, R6, R38, R47, R48, R49, R51, R53, R54, R166, R173, R174, R175, R176, R177, R178, R179, R180, R479, R480, R482, R494, R537, R562	27	4.7k	R0402	—	ERJ-2RKF4701X	Panasonic	RES SMD 4.7K Ω 1% 1/10 W 0402
57	R4, R57, R59, R70, R72	5	0	R0603	—	RC0603JR-070RL	Yageo	Res 1/10 W 0.0 Ω 5% 0603
58	R7, R8, R9, R10, R12, R19, R20, R28, R93, R94, R106, R108, R119, R456, R457, R458, R459, R460, R461, R462, R463, R495, R496, R500, R501, R539, R540, R542, R543, R563, R564, R565, R566, R567, R568, R569, R582, R583, R584, R585, R586, R587	42	0	R0402	—	ERJ-2GE0R00X	Panasonic	RES SMD 0.0 Ω JUMPER 1/10 W 0402
59	R11, R588, R589, R590	1	0	R0402	DNL	ERJ-2GE0R00X	Panasonic	RES SMD 0.0 Ω JUMPER 1/10 W 0402
60	R14, R25, R538, R544, R545, R546, R547, R548, R549	9	2k2	R0402	—	ERJ-2RKF2201X	Panasonic	RES SMD 2.2K Ω 1% 1/10 W 0402
61	R15	1	12k	R0402	—	ERJ-2RKF1202X	Panasonic	RES SMD 12K Ω 1% 1/10 W 0402

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
62	R16, R17, R18, R29, R43, R44, R45, R46, R62, R66, R80, R81, R504, R557, R558, R560	16	10K	R0402	—	ERJ-2GEJ103X	Panasonic	RES SMD 10K Ω 5% 1/10 W 0402
63	R26, R27, R50, R52, R507, R528, R529, R530, R531, R532, R533, R534, R535, R550	14	680R	R0402	—	RMCF0402J T680R	Stackpole Electronics Inc.	RES 680 Ω 1/16 W 5% 0402
64	R30, R31, R32, R509, R559, R561	6	1K	R0402	—	RMCF0402J T1K00	Stackpole Electronics Inc.	RES 1K Ω 1/16 W 5% 0402
65	R33	1	33E	R0603	—	ERJ-3GEYJ330V	Panasonic	Thick Film Resistors 0603 33 Ω 5% AEC-Q200
66	R56	1	100E	R0603	DNL	CRCW06031 00RFKEAHP	Vishay/Dale	Thick Film Resistors - SMD 1/4 W 100 Ω 1% 100 ppm High Power
67	R58, R63, R65, R67	4	51k	RLP-100	—	TNPW04025 1K0BEED	Vishay/Dale	Thin Film Resistors 51K Ω 0.1% 25 ppm
68	R60	1	21.5K	R0402	—	ERJ-2RKF2152X	Panasonic	RES SMD 21.5K Ω 1% 1/10 W 0402
69	R61	1	31.6K	R0402	—	ERJ-2RKF3162X	Panasonic	RES SMD 31.6K Ω 1% 1/10 W 0402
70	R64	1	34K	R0402	—	ERJ-2RKF3402X	Panasonic	RES SMD 34K Ω 1% 1/10 W 0402
71	R73, R74, R86, R87, R92	5	10K	R0402	—	ERJ-2GEJ103X	Panasonic	RES SMD 10K Ω 5% 1/10 W 0402
72	R75	1	3.83K	R0402	—	ERJ-2RKF3831X	Panasonic	RES SMD 3.83K Ω 1% 1/10 W 0402
73	R76	1	8.87K	R0402	—	ERJ-2RKF8871X	Panasonic	RES SMD 8.87K Ω 1% 1/10 W 0402
74	R77	1	34.8K	R0402	—	ERJ-2RKF3482X	Panasonic	RES 34.8K Ω 1/10 W 1% 0402 SMD
75	R78	1	63.4K	R0402	—	ERJ-2RKF6342X	Panasonic	RES 63.4K Ω 1/10 W 1% 0402 SMD
76	R88, R91	2	110K	R0402	—	ERJ-2RKF1103X	Panasonic	RES SMD 110K Ω 0.1% 1/10 W 0402
77	R110, R111, R112, R113, R114, R148, R149, R150, R151, R152	10	4.7k	R0402	DNL	ERJ-2RKF4701X	Panasonic	RES SMD 4.7K Ω 1% 1/10 W 0402
78	R117	1	100K	R0402	—	RMCF0402J T100K	Stackpole Electronics Inc.	RES 100K Ω 1/16 W 5% 0402

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
79	R118	1	100E	R0402	—	TNPW04021 00RBED	Vishay	Thin Film Resistors - SMD 100 Ω .1% 25ppm
80	R121, R122	2	0E	R0402	—	ERJ- 2GE0R00X	Panasonic	RES SMD 0.0 Ω JUMPER 1/10 W 0402
81	R123, R124, R127, R128, R129, R132, R133, R136, R137, R140	10	49.9E	R0402	DNL	CRCW04024 9R9FKED	Vishay Dale	Thick Film Resistors - SMD 1/16 W 49.9 Ω 1%
82	R125, R126, R130, R131, R134, R135, R138, R139	8	0E	R0402	—	ERJ- 2GE0R00X	Panasonic	RES SMD 0.0 Ω Jumper 1/10 W 0402
83	R158, R472	2	240E	R0402	—	ERJ- 2RKF2400X	Panasonic	RES SMD 240 Ω 1% 1/10 W 0402
84	R159, R160, R161, R162, R163, R164, R483, R484, R486, R510, R511, R512, R513, R514, R515, R516, R517, R518, R519, R520, R521, R522, R523, R524, R525, R526, R527	27	49.9E	R0402	—	CRCW04024 9R9FKED	Vishay Dale	Thick Film Resistors - SMD 1/16 W 49.9 Ω 1%
85	R165, R169, R170	3	0E	R0402	—	ERJ- 2GE0R00X	Panasonic	RES SMD 0.0 Ω Jumper 1/10 W 0402
86	R167, R168, R171, R172	4	0E	R0402	DNL	ERJ- 2GE0R00X	Panasonic	RES SMD 0.0 Ω Jumper 1/10 W 0402
87	R230	1	34K	R0402	—	ERJ- 2RKF3402X	Panasonic	RES 34K Ω 1/10 W 1% 0402 SMD
88	R231	1	536K	R0402	—	ERJ- 2RKF5363X	Panasonic Electronic Components	RES 536K Ω 1/10 W 1% 0402 SMD
89	R232	1	100K	R0402	—	ERJ- 2RKF1003X	Panasonic Electronic Components	RES 100K Ω 1/10 W 1% 0402 SMD
90	R464, R465, R466, R467, R469, R470, R471, R551, R552, R553, R554, R555, R570, R571, R574, R575, R576, R577, R578, R579, R580, R581	22	100E	R0402	DNL	TNPW04021 00RBED	Vishay	Thin Film Resistors - SMD 100 Ω 0.1% 25 ppm
91	R474, R475, R477	3	0	R0603	—	ERJ- 3GEY0R00V	Panasonic	Thick Film Resistors - SMD 0603 Zero Ω
92	R481	1	1k	R0402	—	RMCF0402J T1K00	Stackpole Electronics Inc.	RES SMD 1K Ω 5% 1/16 W 0402
93	R502, R503, R505, R506	4	220E	R0402	—	ERJ- 2RKF2200X	Panasonic	RES SMD 220 Ω 1% 1/10 W 0402

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
94	R508	1	470E	R0402	—	CRCW0402470RFKED	Vishay	Thick Film Resistors - SMD 1/16 W 470 Ω 1% 100 ppm
95	R556	1	30.1K	R0402	—	ERJ-2RKF3012X	Panasonic	RES 30.1K Ω 1/10 W 1% 0402 SMD
96	SW1, SW4	2	SYS_RST	4psmd_switch	—	434153017835	Würth	SWITCH TACTILE SPST-NO 0.05 A 12 V
97	SW2	1	PWR	450301014042_switch	—	450301014042	Würth	Slide Switch SPDT Through Hole
98	SW3	1	SW DIP-8	CTS_218-8	Alternate PN : 218-8LPST	97C08SRT	Grayhill Inc.	Dip Switch SPST 8 Position Surface Mount Slide (Standard) Actuator 25 mA 24 VDC
99	TH1, TH2, TH3, TH4	4	ThruHole	MTG125	DNL	—	—	—
100	TP1, TP2, TP3, TP17, TP18, TP25, TP26	7	20mil_SMD	20mil_SMD	DNL	—	—	—
101	TP5, TP6, TP7, TP8, TP9, TP10, TP11, TP12	8	TestPoint	TP50	DNL	—	—	—
102	U1	1	ATSHA204A	ATSHA204A	—	ATSHA204A-MAHDA-T	Atmel Corporation	IC CRYPTO 4.5 KB I2C 8UDFN
103	U2	1	FT2232HL	tqfp64_0p5_12p2x12p2_h1p6	—	FT2232HL	FTDI	USB to UART / FIFO
104	U3	1	M24M01	M24M01	—	M24M01-RMN6P	STMicroelectronics	EEPROM Serial-I2C 1 Mbit 128K x 8 2.5 V/3.3 V/5 V 8-Pin SO N
105	U4	1	93LC56-SO8	so8_50_244	—	93LC56C-I/SN	Microchip	IC EEPROM 2 KBIT 3 MHz 8SOIC
106	U7	1	FUSE	0154004DR T	—	0154004.DR T	Littelfuse	Surface Mount Fuses Fuseblock with fuse 4 A OMNI BLOK 154T
107	U8, U9	2	LT3508EUF	LT3508EUF	—	LT3508EUF#PBF	Linear Technology	IC REG BUCK ADJ 1.4 A DL 24QFN
108	U10, U11	2	LT3085	LT3085E_6DFN	—	LT3085EDCB#PBF	Linear Technology	IC REG LDO ADJ 0.5 A 6DFN
109	U12, U19	2	ddr3-96bga	MT41J64M16TW-093	—	MT41J64M16TW-093	Micron	IC DDR3 SDRAM 1 Gbit FBGA

Item	Reference	Qty	Part	PCB Footprint	Comments	Part Number	Manufacturer	Description
110	U13	1	LP2998-S08	RLP-300	—	LP2998MR/ NOPB	Texas Instruments	Termination Regulator 2.2 V to 5.5 V 8-Pin HSOP EP Tube
111	U17	1	ECP5UM-85F- BG756	LFE5UM- 85F- 7BG756I	—	LFE5UM- 85F- 7BG756I	Lattice Semiconductor Corporation	IC FPGA 84K LUT 1.1 V 756CABGA IND
112	U52	1	N25Q128A13E SE40E	N25Q128_ S08W	Rev B	N25Q128A1 3E5E40E	Micron	IC FLASH 128 Mbit 108 MHz 8SO
			MX25L12835F M2I		Rev C	MX25L1283 5FM2I-10G	Macronix	IC FLASH 128 Mbit 108 MHz 8SO
113	U53	1	ispCLOCK5406 D	ISPCLOCK5 406D	—	ispCLOCK54 06D	Lattice Semiconductor Corporation	ispClock Manager
114	U54	1	LT3680	LT3680_10 QFN	—	LT3680EDD# PBF	Linear	5 V Step down converter
115	X1	1	12MHZ	crystal_4p_ 3p2x2p5	—	7M- 12.000MAAJ -T	TXC	CRYSTAL 12.0000 MHz 18 pF SMD
116	X2	1	KC2520B27.00 00C2GE00	27MHZ_OS C	—	KC2520B27. 0000C2GE0 0	AVX/Kyocera	Standard Clock Oscillators 27 MHz 2.5 V 2.5x2.0 mm SMD
117	X4	1	156.25MHz_L VCMOS	SiT8256AC	—	SiT8256AC- 23-33E - 156.250000 Y	SiTime	125 MHz CMOS MEMS (Silicon) Oscillator Surface Mount 2.25 V ~ 3.6 V 35 mA Enable/Disable
118	X5	1	100_00MHz_L VDS	DSC1123CI 5	—	DSC1123CI5 -100.0000	Microchip Technology/ Micrel	100 MHz LVDS MEMS (Silicon) Oscillator Surface Mount 2.25 V ~ 3.6 V 32 mA Enable/Disable
119	ECP5 Video Processor Board REVB PCB	1	—	—	—	305-PD-16- 1002	Pactron	—

Appendix C. ECP5 VIP Processor Board Revision B

Differences between the Revision B board and later revisions.

- The DDR interface has individual CKE signals for each DDR3 device, DDR_CE0 and DDR_CE1. Later revisions of the board only have DDR_CE0 which is routed to CKE of both DDR3 devices. See [Figure C.1](#) for the schematic of Revision B.
- The ECP5 SPI interface is routed directly to the downstream connector J12. Later revisions of the board have this interface open with the ability to bridge using 0 Ω resistors, R588, R589 and R590. See [Figure C.2](#) for the schematic of Revision B.

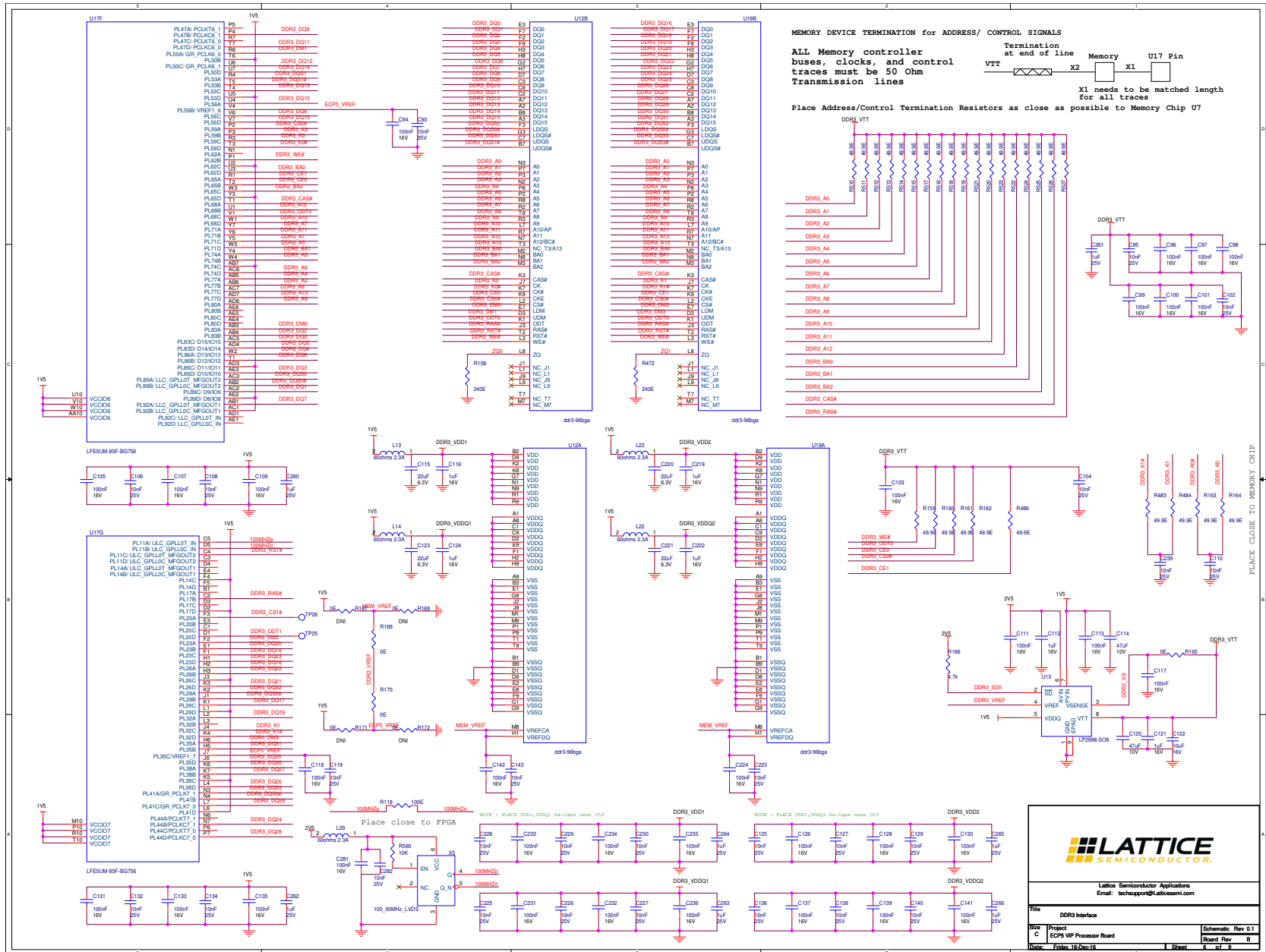


Figure C.1. DDR3 Interface Revision B

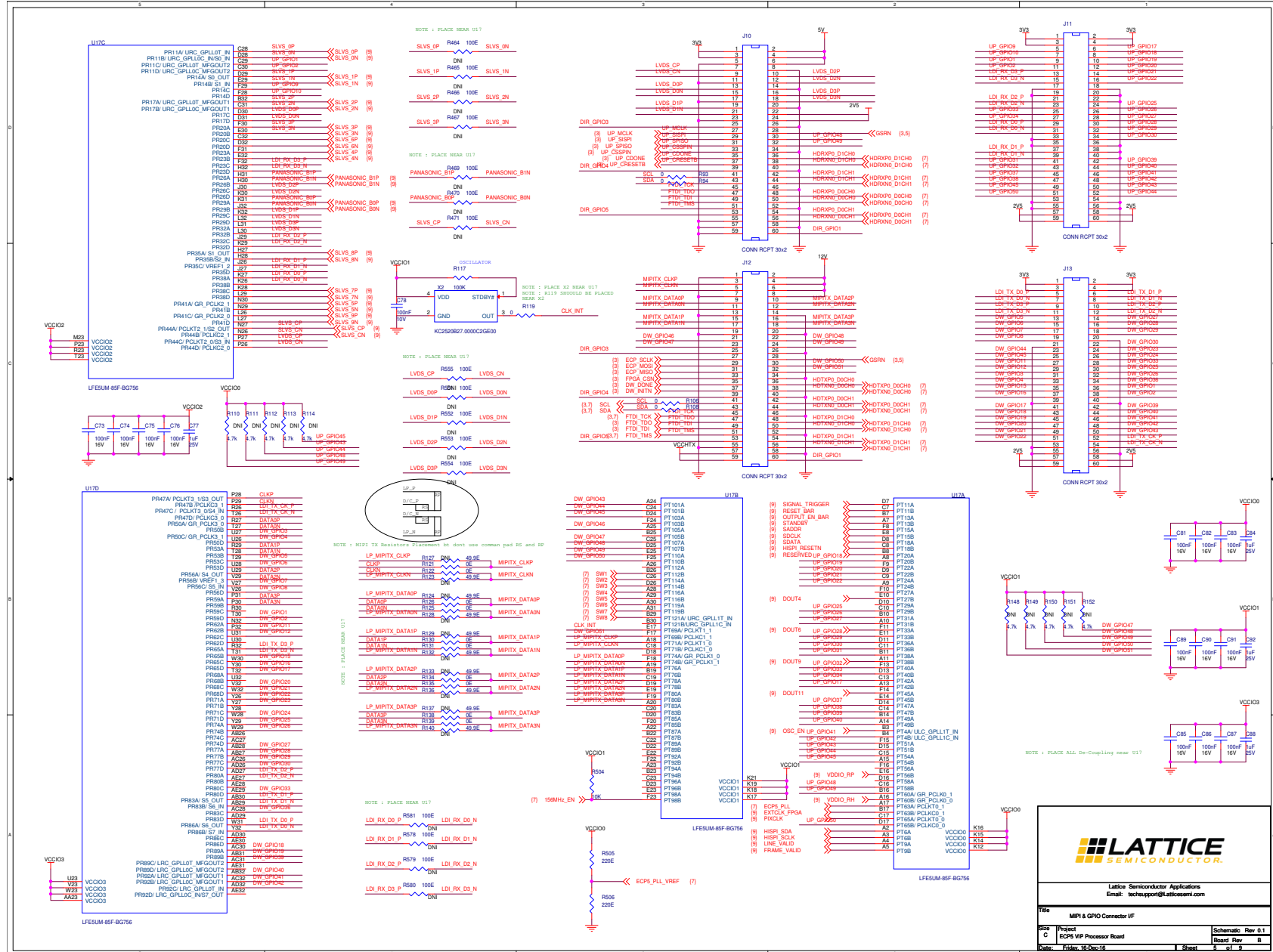


Figure C.2. MIPI and GPIO Connector Interface Revision B

References

For more information, refer to:

- [ECP5 and ECP5-5G Family Data Sheet \(FPGA-DS-02012 previously DS1044\)](#)
- [Lattice Embedded Vision Development Kit User Guide \(FPGA-UG-02015\)](#)
- [CrossLink VIP Input Bridge Board \(FPGA-EB-02002\)](#)
- [HDMI VIP Output Bridge Board \(FPGA-EB-02003\)](#)

For more information on ispClock, visit www.latticesemi.com/ispclock.

Technical Support Assistance

Submit a technical support case through www.latticesemi.com/techsupport.

Revision History

Revision 1.6, April 2021

Section	Change Summary
All	Changed SERDES to <i>SerDes</i> .
ECP5 Interface Support	Updated note and Figure 4.1 in DDR3 Interface section.

Revision 1.5, December 2020

Section	Change Summary
Disclaimers	Added this section.
ECP5 Interface Support	Added information on the use of 16 bit DDR3 in the DDR3 Interface section.
All	Minor adjustments in formatting and style

Revision 1.4, February 2018

Section	Change Summary
Introduction	<ul style="list-style-type: none"> Updated board pictures to Rev C: <ul style="list-style-type: none"> Figure 1.1. Top View of ECP5 VIP Processor Board and its Key Components Figure 1.2. Bottom View of ECP5 VIP Processor Board
Programming Circuit	Added Table 3.1 . SPI Flash Memory
Power Supply	<ul style="list-style-type: none"> Removed Power LEDs table (previously Table 5.1). Added information to Table 5.1. Device Power Rail Summary.
Appendix A. ECP5 VIP Processor Board Schematics to Revision C	Updated schematic diagrams.
Appendix C. ECP5 VIP Processor Board Revision B	Added this section

Revision 1.3, July 2017

Section	Change Summary
ECP5 Interface Support	Added note to DDR3 Interface section.

Revision 1.2, June 2017

Section	Change Summary
Ordering Information	Updated this section.

Revision 1.1, May 2017

Section	Change Summary
Introduction	Updated board pictures to Rev B: <ul style="list-style-type: none"> Figure 1.1. Top View of ECP5 VIP Processor Board and its Key Components Figure 1.2. Bottom View of ECP5 VIP Processor Board

Revision 1.0, April 2017

Section	Change Summary
All	Initial release.



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